

Electronic Acknowledgement Receipt

EFS ID:	8698998
Application Number:	09523990
International Application Number:	
Confirmation Number:	6138
Title of Invention:	Method of manufacture and identification of semiconductor chip marked for identification with internal marking indicia and protection thereof by non-black layer and device produced thereby
First Named Inventor/Applicant Name:	Mou-Shiung Lin
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Filer Authorized By:	Dennis Alan Duchene
Attorney Docket Number:	085027-0026
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Time Stamp:	20:53:30
Application Type:	Utility under 35 USC 111(a)

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Payment was successfully received in RAM	\$940
RAM confirmation Number	9701
Deposit Account	502624
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File Listing:

Document Number	Document Description	File Name	File Size(Bytes)/ Message Digest	Multi Part /.zip	Pages (if appl.)
1	Transmittal Letter	085027_0026_tm.pdf	22225 35af3f6034c2b6d80f0d4ddc300286725e b1ef5	no	1
Warnings:					
Information:					
2	Request for Continued Examination (RCE)	085027_0026_rce.pdf	37324 a897052f5f3cb3c551680f54e8f9931d5 1d676	no	1
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3	Transmittal Letter	085027_0026_ids.pdf	23396 8a6c52b80c8a441d510a6c24b61c3b38 986a9	no	2
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Information:					
4	Information Disclosure Statement (IDS) Filed (SB/08)	085027_0026_idslist.pdf	63696 576ec1a1827080085a858194d75c341b1da0 60700	no	3
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5	Request for Corrected Filing Receipt	085027_0026_FRrequest.pdf	24145 f70aff22ba72214f948cf9a6ca237d3a76f 25e8	no	2
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6		085027_0026_amendment.pdf	85899 6ec7b511956d4127b44d799679a8f7efdc8a e066	yes	12
	Multipart Description/PDF files in .zip description				
	Document Description		Start	End	
	Amendment Submitted/Entered with Filing of CPA/RCE		1	1	
	Claims		2	4	

	Applicant Arguments/Remarks Made in an Amendment	5	12		
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7	NPL Documents	1.pdf	2254221 072127b124142b87448b36305577a0047281002	no	4
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9	NPL Documents	3.pdf	4517666 1a140bd37c7b154732bd4b4c4129ab0baa4eb74	no	7
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13	NPL Documents	7_ROESCH_Cycling_Copper_Flip_Chip_Connects.pdf	1142794 811203707462423c7a041aef39c24a5e4578ab27	no	8
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Information:					
Total Files Size (in bytes):			41064693		
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